

# CIR-S4DVSW2608G (5 fh" Bc "r% ) ) - %

DDR4 VLP-DIMM 2666MHz 8GB

## Description

CIR-S4DVSW2608G is a CMOS Double Data Rate IV (DDR4) Synchronous DRAM module, in Fine Ball Grid Array (FBGA) packages on a 288pin glass-epoxy substrate.

DDR4 unbuffered UDIMM series offers fully synchronous operations referenced to both rising and falling edges of the clock. The data paths are internally pipelined and 8-bit prefetched to achieve very high bandwidth.

## Specifications

Density	8GB
Pin Count	288pin
Type	Unbuffered
Dimensions	133.35mm x 18.75mm
ECC	non-ECC
Component Config.	1G x 8 bit
Data Rate	2666 MHz
CAS Latency	19
Voltage	1.2V
PCB Layers	8
Operating Temp.(TCASE)	0°C~+85°C
Module Ranks	Single Rank

## Features

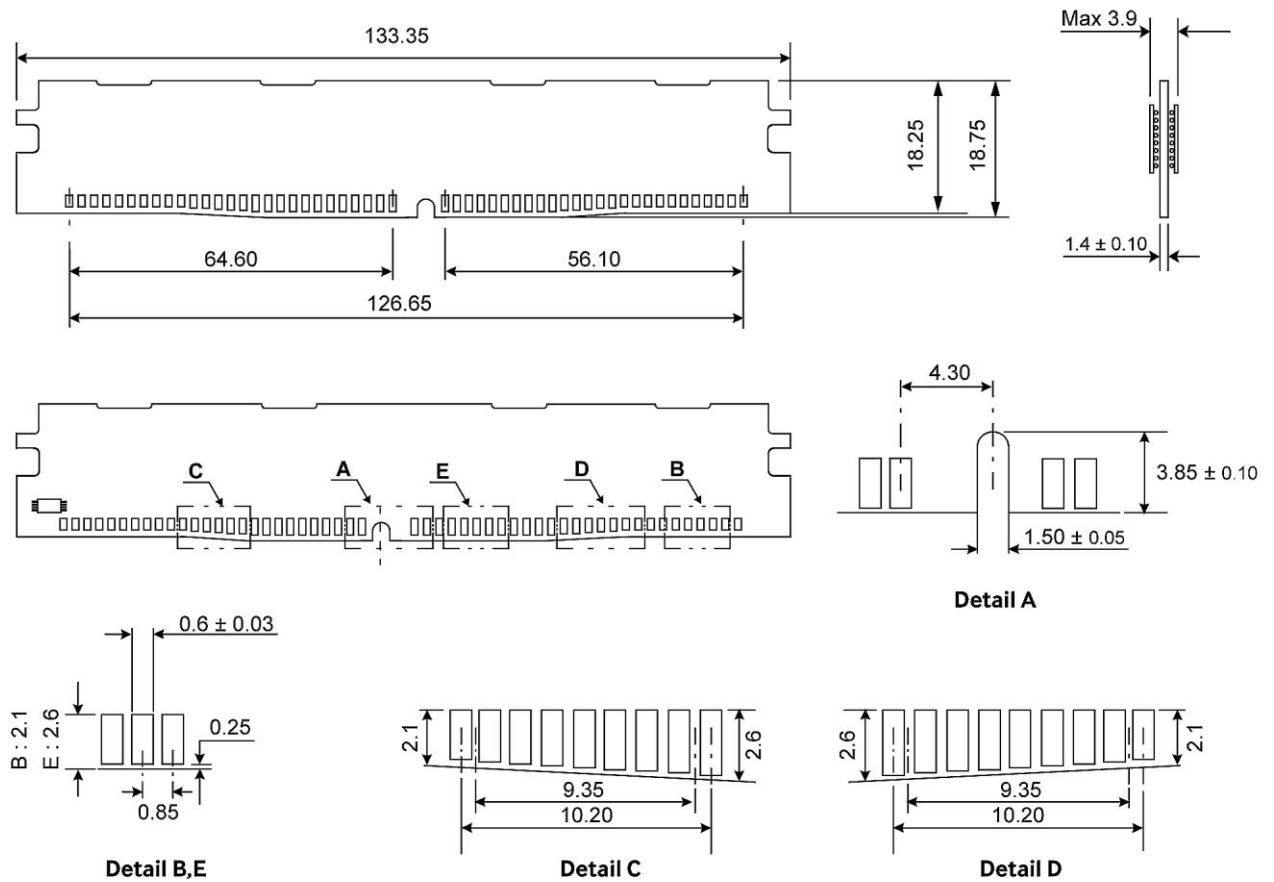
- JEDEC Standard 288-pin Dual In-Line Memory Module
- Inputs and Outputs are SSTL-12 compatible
- VDD=VDDQ = 1.2V±0.06V (1.14V~1.26V)
- Low-Power auto self-refresh (LPASR)
- SDRAMs have 16 internal banks for concurrent operation (4 Bank Group of 4 banks each)
- Programmable CAS Latency(posted CAS): 11,12,13,14,15,16,17,18,19
- Normal and Dynamic On-Die Termination for data, strobe and mask signals.
- Data bus inversion (DBI) for data bus
- Fixed burst chop (BC) of 4 and burst length (BL) of 8 via the MRS
- Selectable BC4 or BL8 on-the fly (OTF)
- Fly-By topology
- Terminated control, command and address bus
- On-die VREFDQ generation and Calibration
- Operation temperature - (0°C~85°C)
- RoHs and Halogen free

### Speed Grade

Frequency Grade	Data Transfer Rate	CAS Latency Support								CL-tRCD-tRP
		CL11	CL12	CL13	CL14	CL15	CL16	CL17	CL19	
DDR4-2666	PC4-21300	1600	1600	1866	1866	2133	2133	2400	2666	19-19-19

### Package Dimensions

Unit: mm



Tolerances : ± 0.15mm unless otherwise specified